



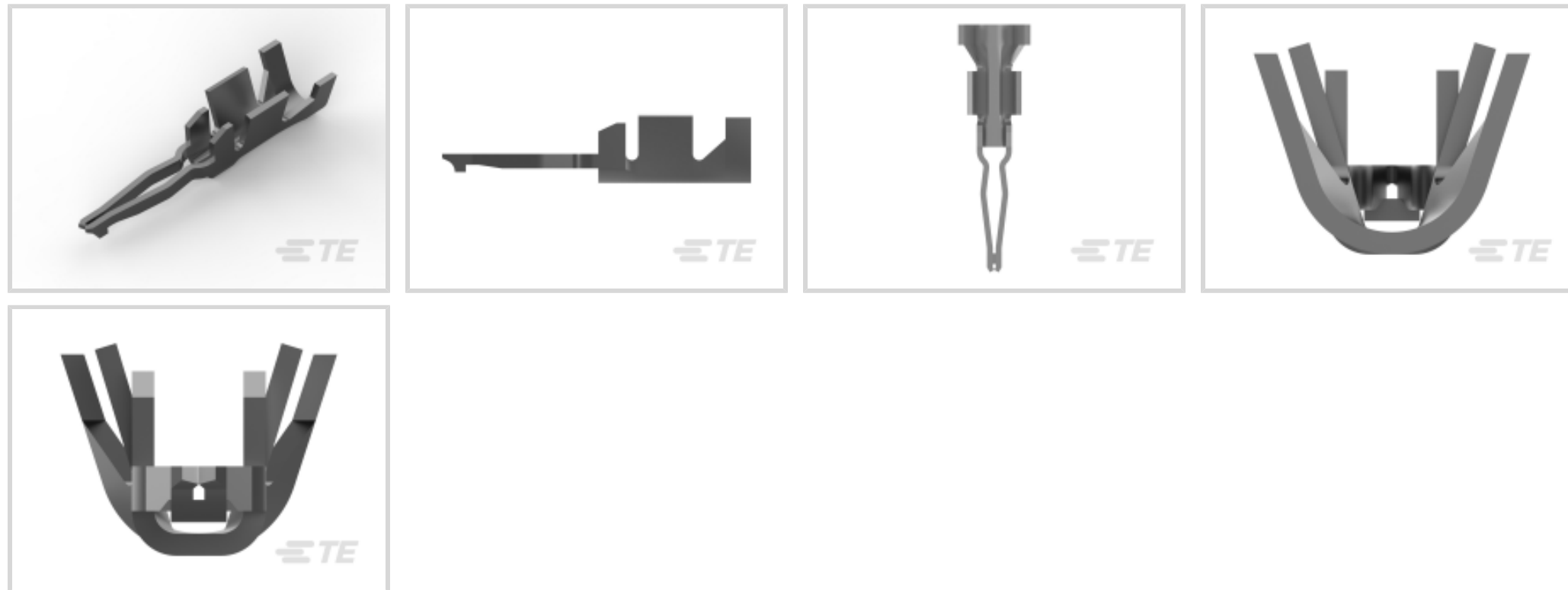
AMP-IN

TE Internal #: 172782-5

Pin Contact, Tin (Sn), 26 – 22 AWG, .12 – .4 mm² Wire, Crimp, Brass, Signal, -40 – 105 °C [-40 – 221 °F]

[View on TE.com >](#)

Connectors > Contacts > Connector Contacts



Contact Type: **Pin**

Contact Mating Area Plating Material: **Tin (Sn)**

Wire Contact Termination Area Plating Material: **Tin**

Wire Size: **.12 – .4 mm²**

Features

Electrical Characteristics

Insulation Resistance	1000 MΩ
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Contact Features

Mating Tab Width	.5 mm[.02 in]
Contact Type	Pin
Contact Mating Area Plating Material	Tin (Sn)
Wire Contact Termination Area Plating Material	Tin
Contact Base Material	Brass
Contact Current Rating (Max)	2.5 A, 4 A

Termination Features

Termination Method to Wire & Cable	Crimp
Product Terminates To	Wire & Cable

Mechanical Attachment

Wire Insulation Support	With
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Dimensions

Compatible Insulation Diameter Range	1.4 – 1.5 mm[.055 – .059 in]
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Wire Size	.12 – .4 mm ²
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Usage Conditions

Operating Temperature Range	-40 – 105 °C[-40 – 221 °F]
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Operation/Application

Circuit Application	Signal
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Packaging Features

Packaging Method	Strip
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Packaging Quantity	20000
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Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant
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EU ELV Directive 2000/53/EC	Compliant
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China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
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EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2025 (247) Candidate List Declared Against: JAN 2025 (247) Does not contain REACH SVHC
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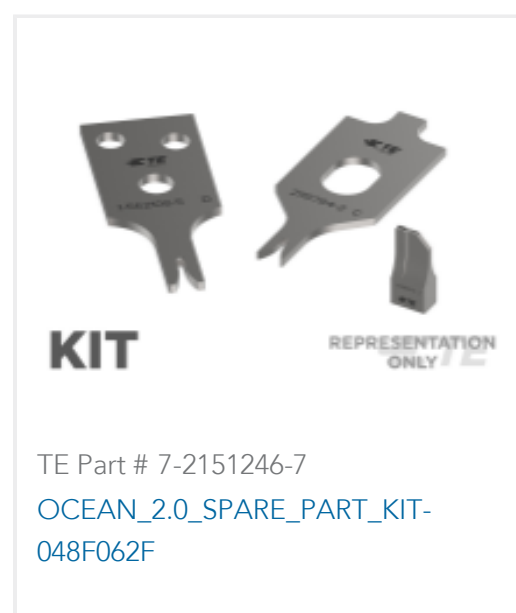
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
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Solder Process Capability	Wave solder capable to 265°C
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Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts



Customers Also Bought



Documents

Product Drawings

LOW PROFILE MINI AMP-IN

English

CAD Files

3D PDF

3D

Customer View Model

[ENG_CVM_CVM_172782-5_N.2d_dxf.zip](#)

English

Customer View Model

[ENG_CVM_CVM_172782-5_N.3d_igs.zip](#)

English

Customer View Model

[ENG_CVM_CVM_172782-5_N.3d_stp.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Datasheets & Catalog Pages



PRINTED CIRCUIT BOARD TERMINALS AND DISCONNECTS

English

Product Specifications

[Crimping of Low Profile, Mini AMP-IN* Terminals](#)

Japanese

Application Specification

Japanese